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(21)

Lewis  
9/22/00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Kikuta, K.

Serial No.: 09/584,739

Group Art Unit: 2814

Filing Date: June 1, 2000

Examiner: Unknown

For: COPPER-ALLOY INTERCONNECTION LAYER

Assistant Commissioner of Patents  
Washington, D.C. 20231

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SUBMISSION OF FORMAL DRAWINGS

Sir:

Submitted herewith are twenty-one (21) sheets of formal drawings comprising figures 1A - 6D for the above-identified patent application. Please substitute these formal drawings for the drawings which were filed with the application.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Sean M. McGinn".

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Registration No. 34,386

Date: 9/14/00

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FIG. 1A prior art

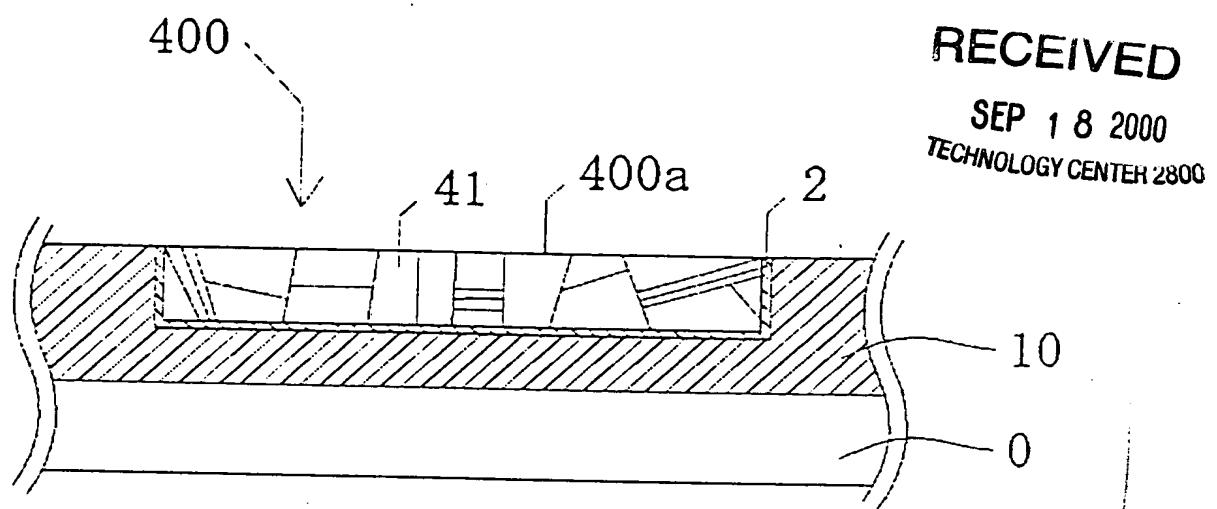


FIG. 1B prior art

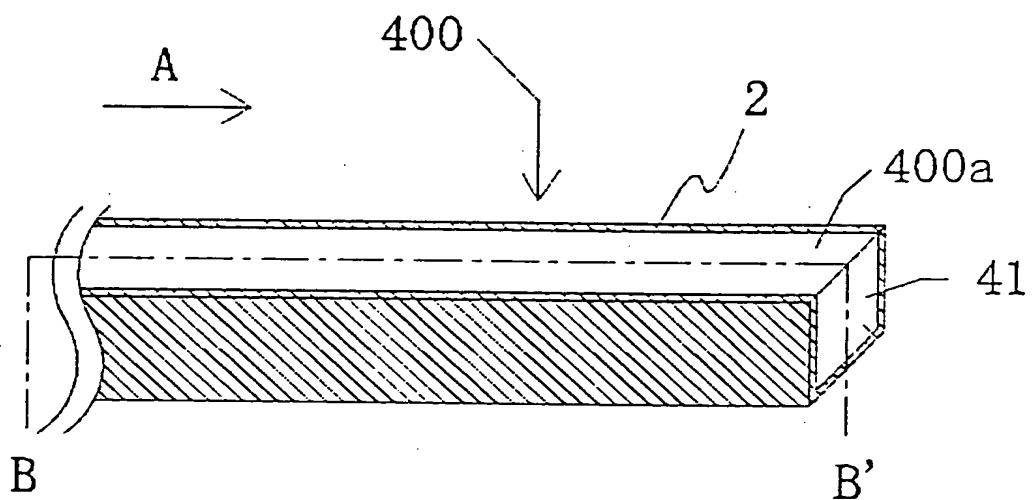


FIG. 1C prior art

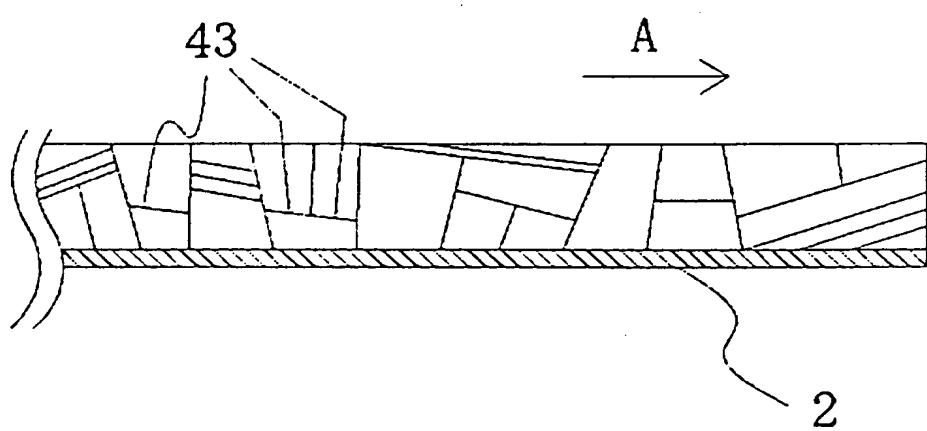


FIG. 2A prior art

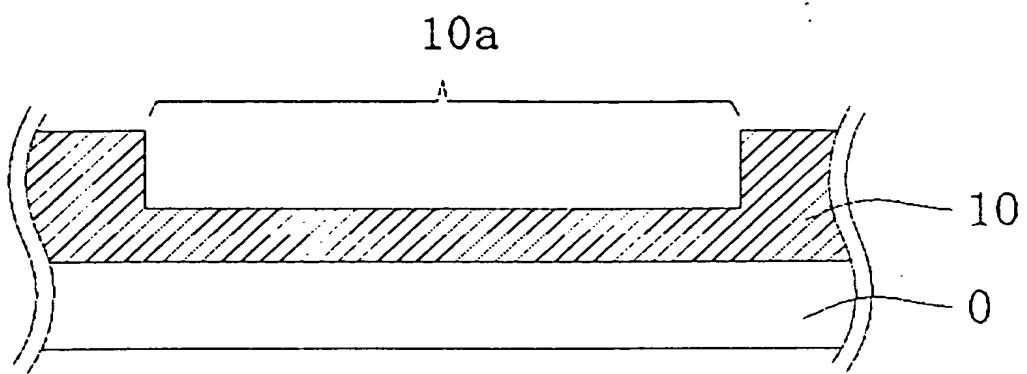


FIG. 2B prior art

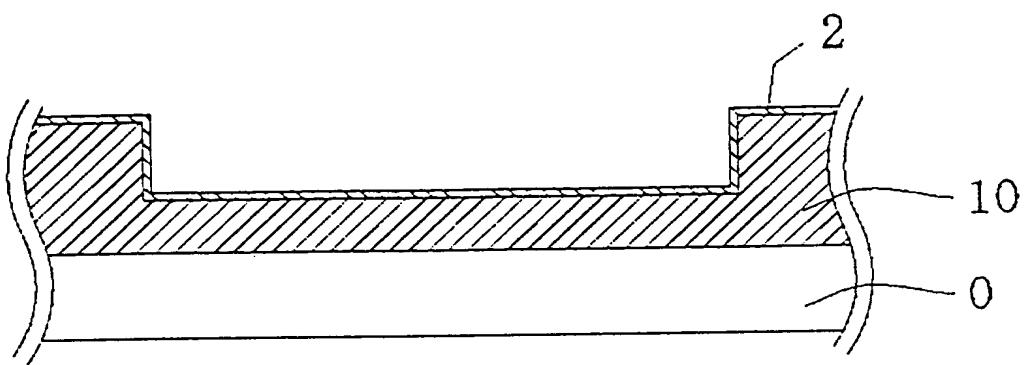


FIG. 2C prior art

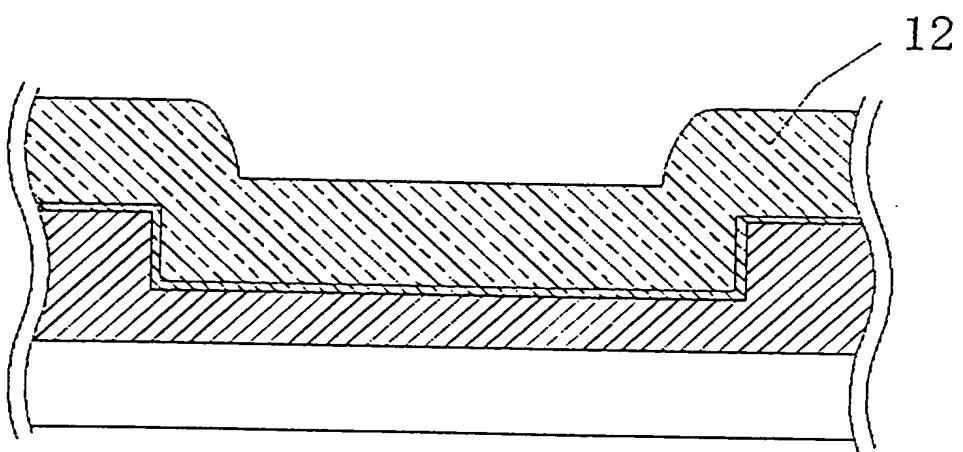
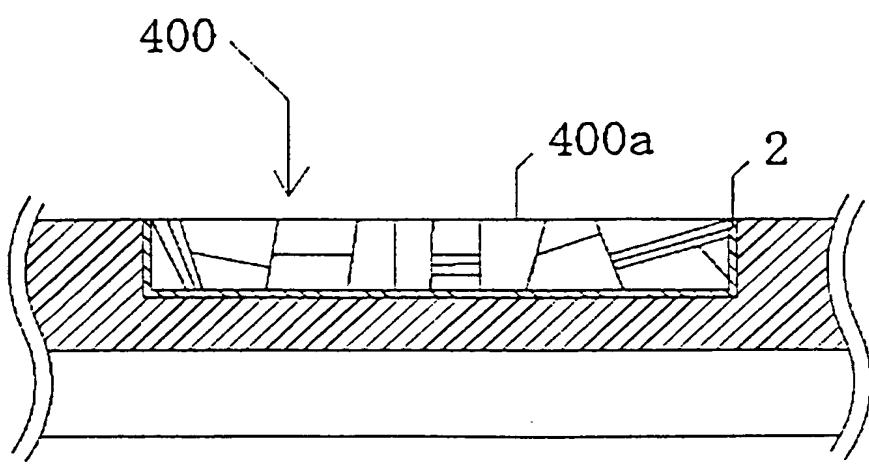
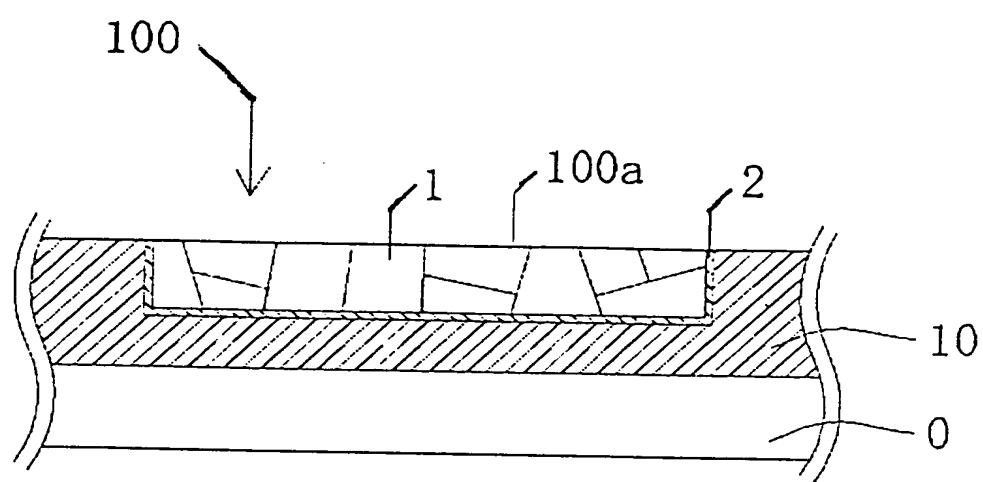


FIG. 2D prior art



**FIG. 3A**

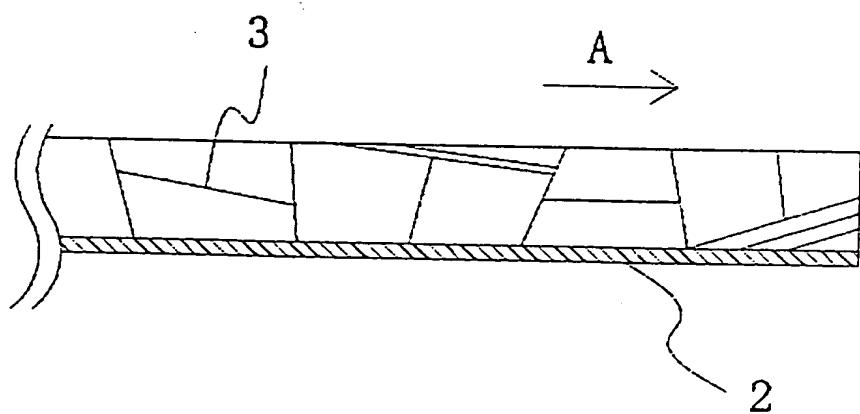
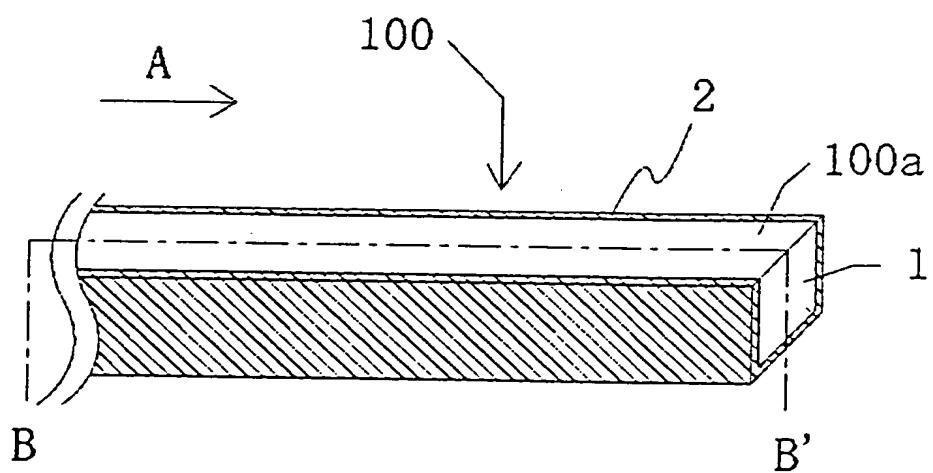
**FIG. 3B**

FIG. 3C



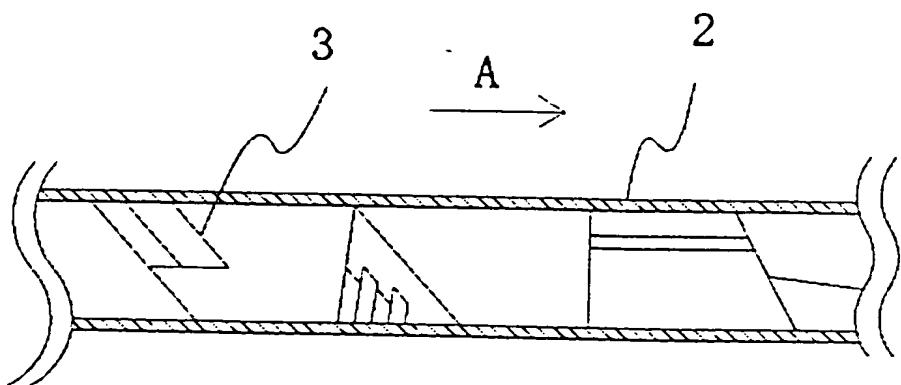
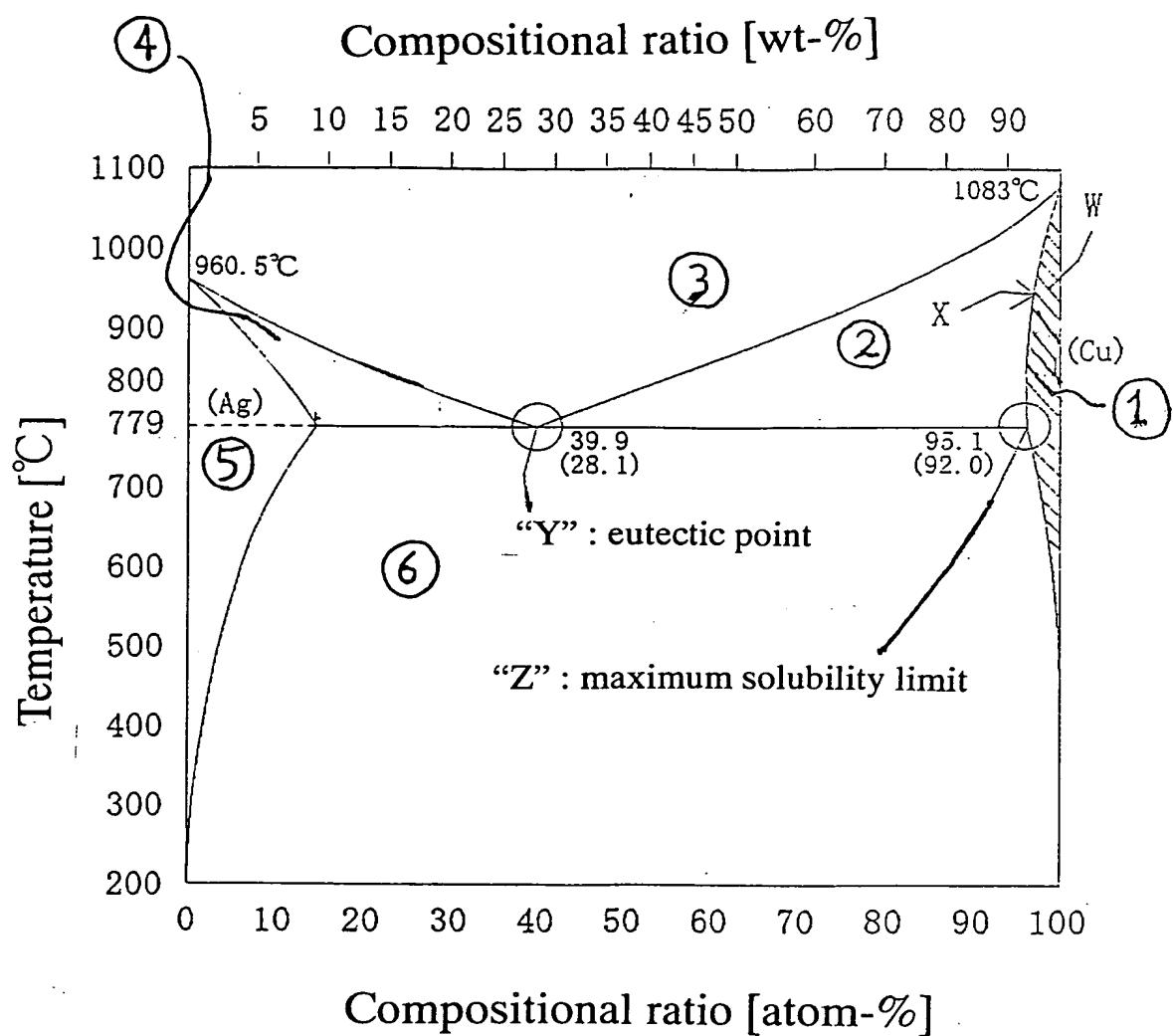
**FIG. 3D**

FIG. 4



① : a solid phase of Cu.

② : co-existence of a liquid phase of Ag and Cu and a solid phase of Cu.

③ : a liquid phase of Ag and Cu.

④ : co-existence of a liquid phase of Ag and Cu and a solid phase of Ag.

⑤ : a solid phase of Ag.

⑥ : a solid phase of Ag and Cu.

# FIG. 5A

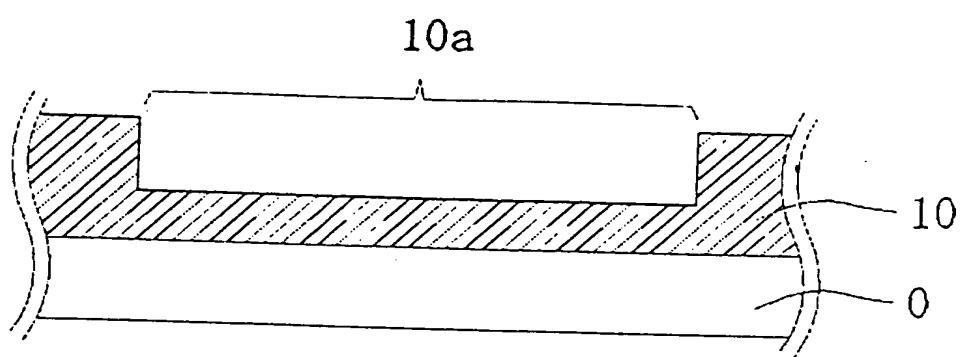
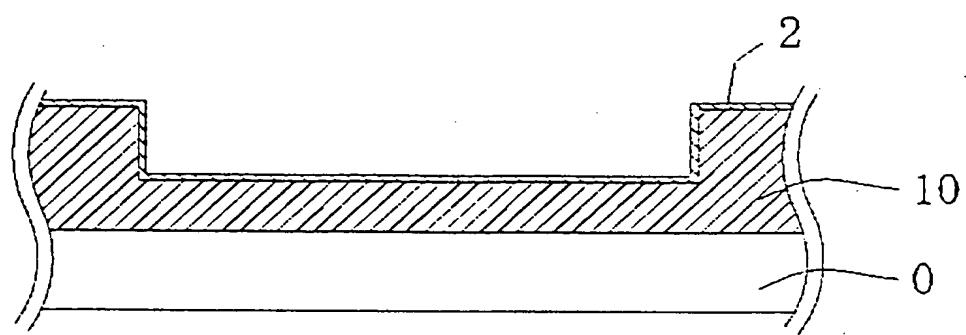


FIG. 5B



# FIG. 5C

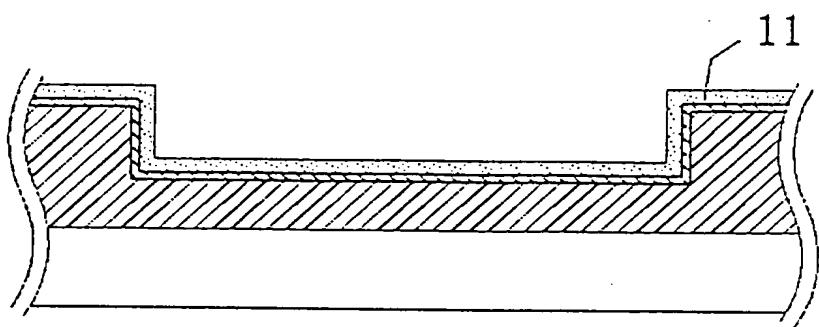


FIG. 5D

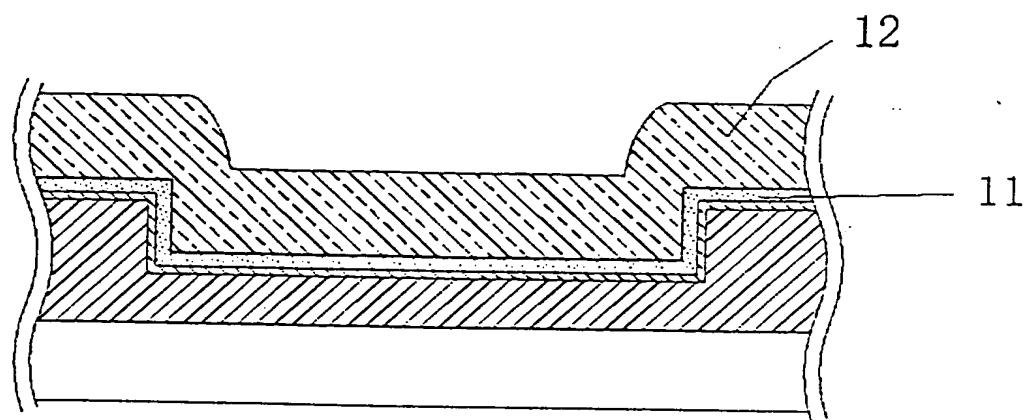


FIG. 5E

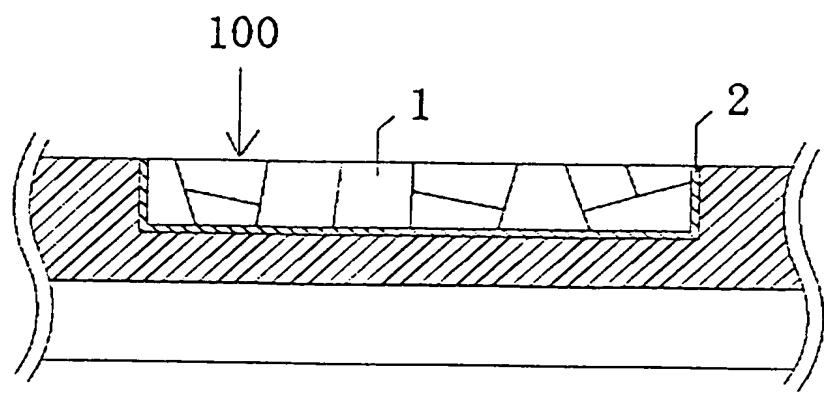


FIG. 6A

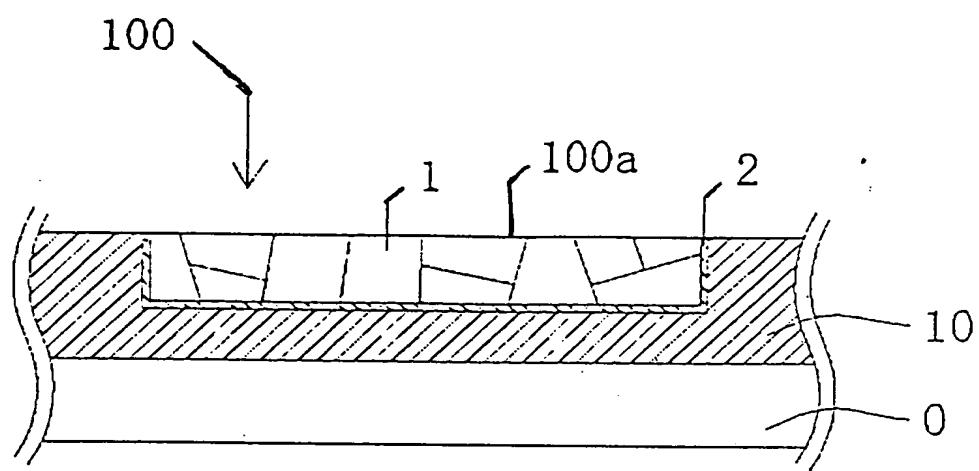


FIG. 6B

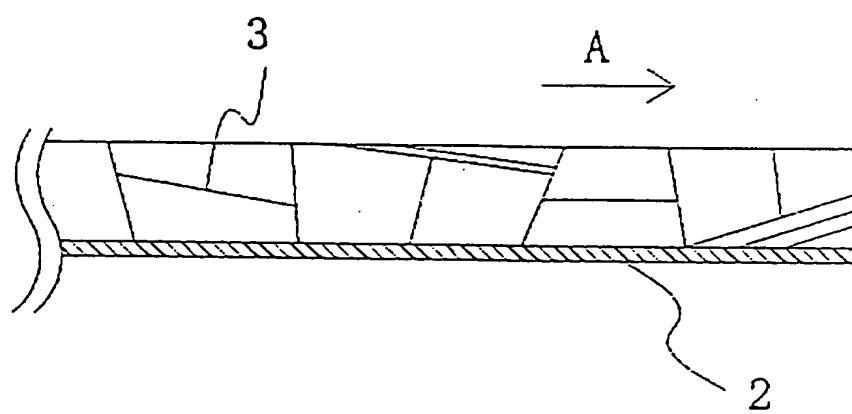


FIG. 6C

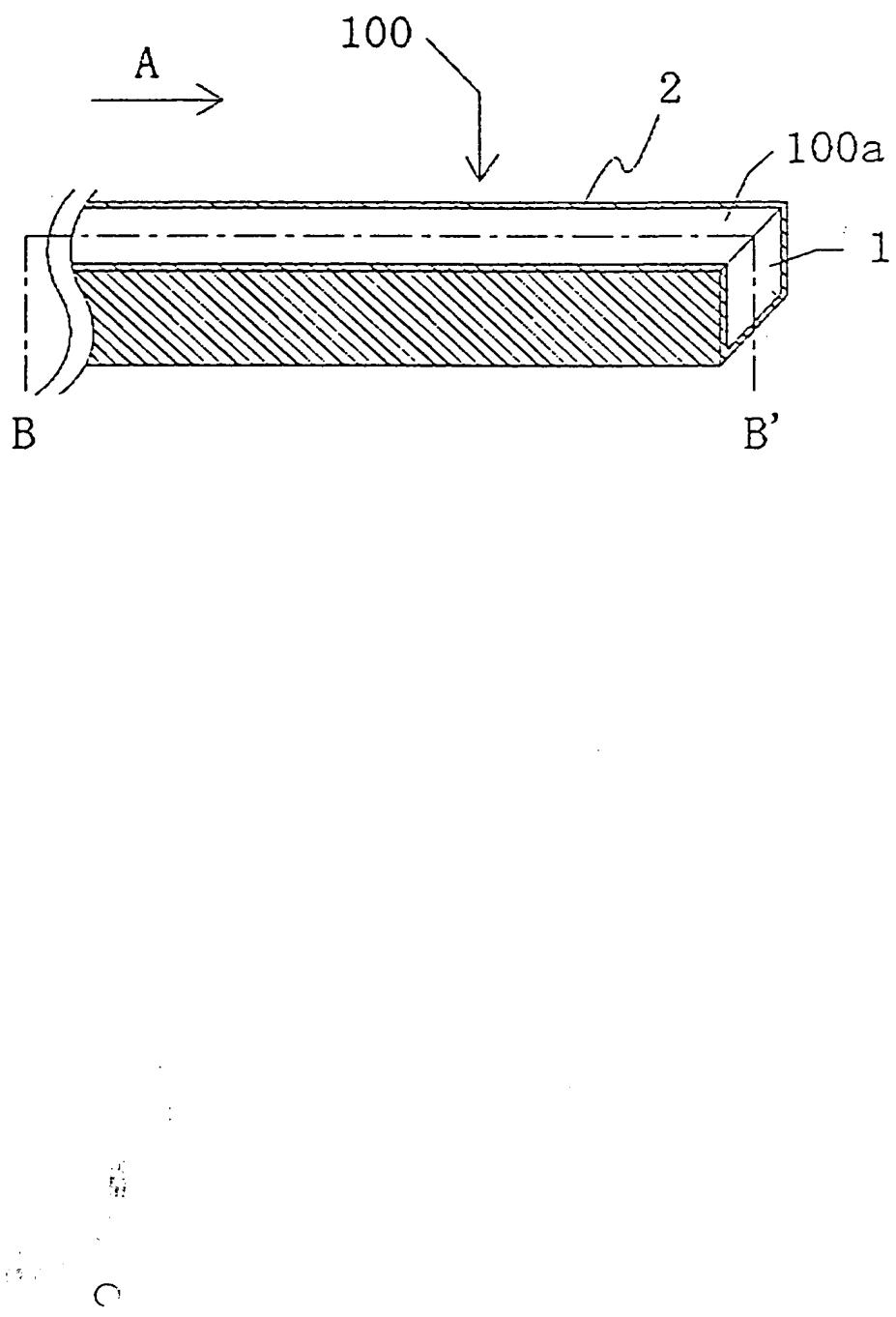


FIG. 6D

